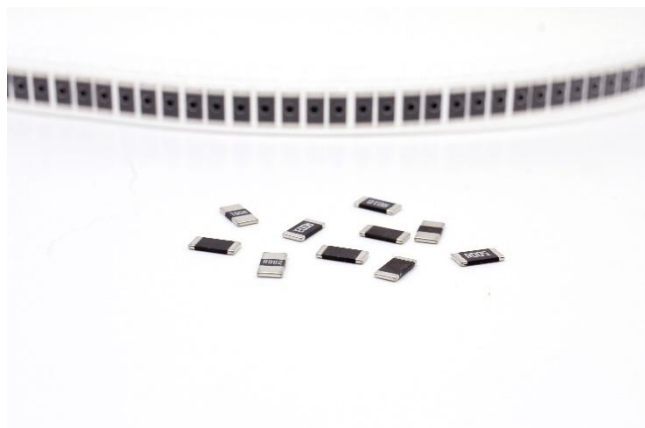




General

- Chip size from 1206 to 2512
- Resistance value from 0.5mΩ to 500mΩ
- Low thermal EMF
- Low inductance 0.5nH to 5nH
- Low TCR
- Lead free, RoHS compliant for global
- Applications and halogen free

Application

- Switching model power supply
- Battery pack
- Notebook, personal computer
- Test Instrument
- Power Amplifier

Electrical Specifications

Type	Power Rating at 70°C(W)	Resistance Range (mΩ)	TCR (ppm/°C)	Resistance tolerance	Operation Temp. Range
2512	2、3	0.5	±100	±0.5%(D) ±1%(F) ±5%(J)	-55°C~+170°C
	2、3	1	±100		
	2	1.5~500	±50		
	3	1.5~300	±50		
2512 (Long Electrode)	3	3	±50	±1%(F)、±2%(G) ±5%(J)	-55°C~+170°C
1206	1	2~50	±50	±0.5%(D) ±1%(F)	

Part Number information

SMR 25 M 2 F R010 T 00

【1】 【2】 【3】 【4】 【5】 【6】 【7】 【8】

【1】 Series Name:SART Metal Current Sensing Chip Resistors

【2】 Chip size:12:120625:2512

【3】 Material Code: M:MnCu N:NiCu S:CuMnSn

【4】 Power Code: 1:1W 2:2W 3:3W

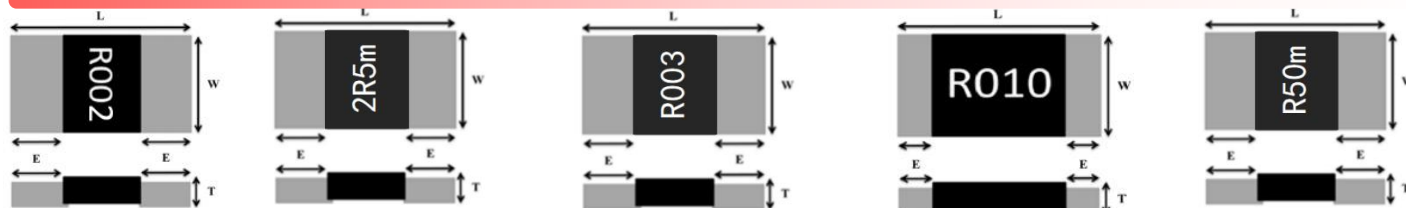
【5】 Resistance Tolerance: D:±0.5%F:±1%G:±2%J:±5%

【6】 Resistance Code:R002=2mΩ、R010=10mΩ、2L50=2.5mΩ、0L50=0.5mΩ

【7】 PackagingCode:T:Tape & Reel、B:Bulk Pack

【8】 Remarks:00: Only For 2512-3W Long Electrode(R003) /01: Only For 2512-3W Small Electrode(R002)

Dimensions



2512(1≤R<3mΩ)

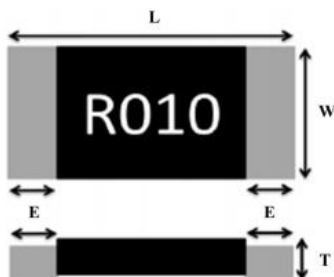
2512(2.5mΩ)

2512 Long Electrode(3mΩ)

2512(2≤R≤500mΩ)

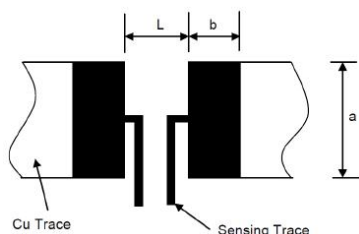
2512(0.5mΩ)

Type	Resistance Range (mΩ)	L (mm)	W (mm)	T (mm)	E (mm)
2512	0.5	6.40±0.20	3.20±0.20	0.90±0.20	2.50±0.20
2512	1≤R<3	6.40±0.20	3.20±0.20	0.80±0.20	2.00±0.20
	2≤R≤500				1.00±0.30
2512(Long Electrode)	3	6.40±0.20	3.20±0.20	0.90±0.20	2.00±0.30



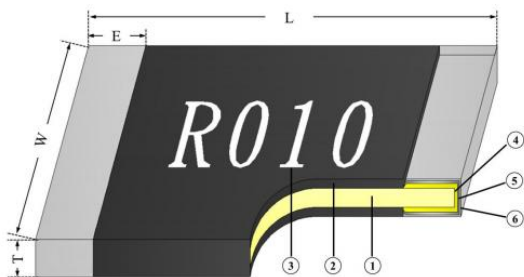
Type	Resistance Range (mΩ)	L (mm)	W (mm)	T (mm)	E (mm)
1206	2~50	3.20±0.20	1.60±0.20	0.70±0.20	0.5±0.30

Recommended Land Patterns



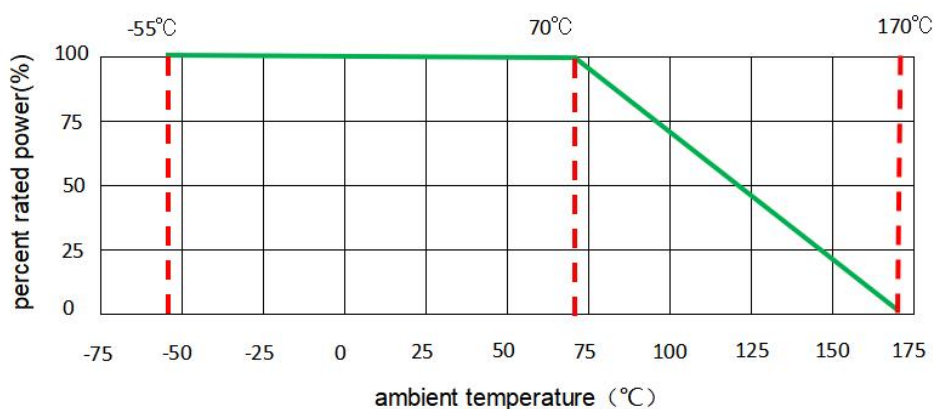
Type	Resistance Range (mΩ)	a (mm)	b (mm)	L (mm)
2512	0.5	4.00	3.10	1.30
	1≤R<3	4.00	3.10	1.80
	2≤R≤500	4.00	2.10	4.10
2512(Long Electrode)	3	4.00	3.10	1.80
1206	2~50	1.80	1.70	1.60

Materials



No.	Materials
1	Metal Alloy
2	Epoxy
3	Epoxy
4	Cu
5	Ni
6	Sn

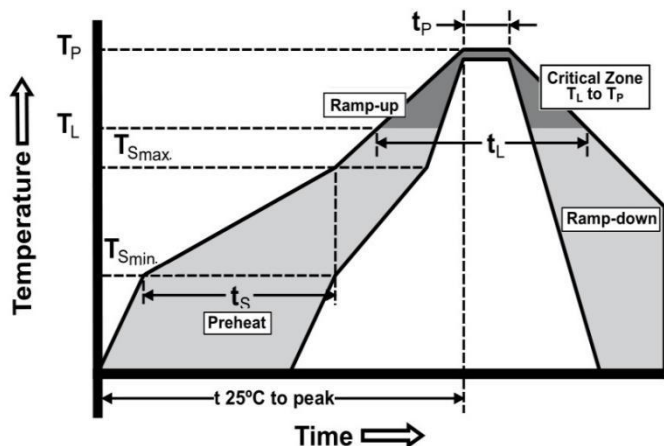
Power Derating Curve



Recommended Solder Curve

1. Infrared Reflow

- Temperature: 260°C.
- Time: 10 sec Max.
- Recommend Reflow profile:



Profile Feature	Pb-Free Assembly
Average Ramp-up Rate (Tsmax to Tp)	3°C/sec Max.
Preheat Temperature Min. (Tsmin) Temperature Max. (Tsmax) Time (ts) (Tsmin to Tsmax)	150°C 200°C 60sec~120sec
Peak Temperature (Tp)	260°C
Time (tp) within 5°C of actual Peak Temperature (Tp)	10sec Max
Liquidous temperature (TL)	217°C
Time at liquidous (TL)	60sec~150sec
Ramp-down Rate	6°C/sec Max.
Time 25°C to peak Temperature	8 min Max.

2. Wave soldering 3. Hand Soldering

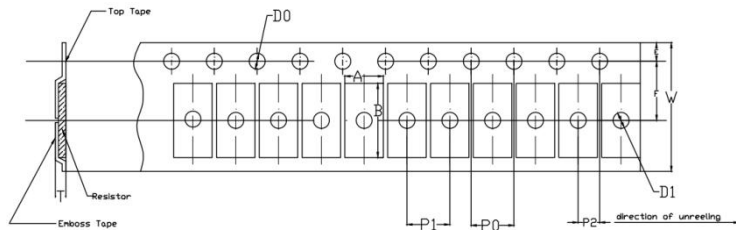
- Reservoir Temperature: 260°C • Temperature: 350°C
- Time in Reservoir: 10sec Max. • Time: 3sec Max.

Product Characteristics

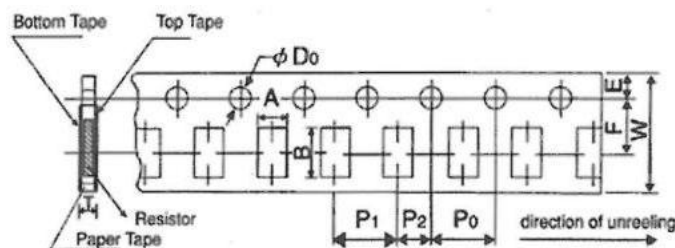
Item	Test condition/ Methods	Performance	Standard
Resistance	Measuring resistance value at room temperature 25℃ ±5℃	Refer to SART Spec	IEC60115-1 4.5
Temperature coefficient of resistance	$TCR = \frac{R-R_0}{R_0(T_2-T_1)} \times 10^6$ $\frac{T_1}{T_2}$ Test temperature: +25℃~+125℃	Refer to SART Spec	IEC60115-1 4.8
Short time Overload	5 times the rated power for 5 sec	$ \Delta R \leq 1.0\%$	IEC 60115-1 4.13
Resistance to Soldering Heat	260℃± 5℃, time: 10 sec±1 sec	$ \Delta R \leq 0.5\%$	MIL-STD-202 Method 210
Solderability	Dip the terminal in a flux and then dip into a soldering bath at 245℃±5℃ for 2sec~3sec	Min 95% coverage	J-STD-002B Test B
Thermal shock	-55℃(30min)/+125℃(30min), 1000 cycles	$ \Delta R \leq 1.0\%$	MIL-STD-202 Method107G
Low temperature storage	-55℃±2℃, 1000hours	$ \Delta R \leq 1.0\%$	IEC60115-1 4.23.4
High Temperature storage	170℃±2℃, 1000hours	$ \Delta R \leq 1.0\%$	MIL-STD-202 Method 108
Moisture with load	+85℃, 85% RH, 1000hours, at 10% rated power 1.5 hours "ON", 0.5 hours "OFF"	$ \Delta R \leq 1.0\%$	MIL-STD-202 Method106G
Vibration	5g's for 20min, 12cycles, 10-2000Hz	$ \Delta R \leq 0.5\%$	MIL-STD-202 Method 204
Load life	70℃± 2℃, 1000 hours, at rated power 1.5 hours "ON", 0.5 hours "OFF"	2512(Long Electrode): $ \Delta R \leq 2.0\%$ Others: $ \Delta R \leq 1.0\%$	MIL-STD-202 Method 108
Board Flex	Epoxy thickness 1.6mm, Fulcrums distance 90mm, Bending width : 2mm; Duration: 60sec±5sec	$ \Delta R \leq 0.5\%$	IEC 60115-1 4.33

Packaging

1. Embossed Tape Dimensions

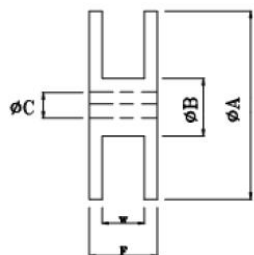


Type	A (mm)	B (mm)	W (mm)	F (mm)	E (mm)
2512	$3.60 \pm_{0.18}^{0.20}$	6.90 ± 0.20	12.00 ± 0.20	5.50 ± 0.05	1.75 ± 0.10
Type	P1 (mm)	P2 (mm)	P0 (mm)	D0/D1 (mm)	T (mm)
2512	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.05	$1.50 \pm_0^{0.10}$	1.00 ± 0.15



Type	A (mm)	B (mm)	W (mm)	F (mm)	E (mm)
1206	2.00 ± 0.15	3.60 ± 0.20	8.00 ± 0.20	3.50 ± 0.05	1.75 ± 0.10
Type	P1 (mm)	P2 (mm)	P0 (mm)	D0 (mm)	T (mm)
1206	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	$1.50 \pm_0^{0.10}$	0.84 ± 0.10

2. Reel Dimensions



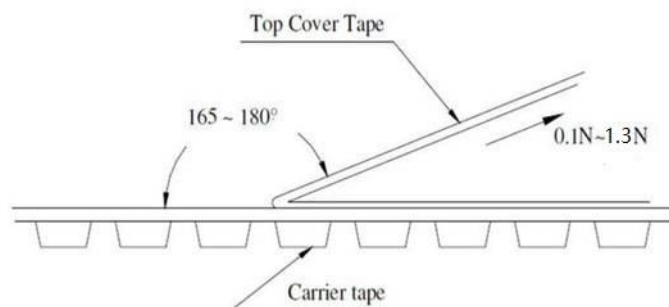
Reel

Type	Φ A (mm)	Φ B (mm)	Φ C (mm)	F (mm)	W (mm)
2512	178.00±2.00	60.00±1.00	13.50±0.50	15.40±1.00	13.00±0.30
1206	178.00±2.00	60.00±1.00	13.50±0.50	11.40±0.10	9.00±0.30

3. Quantity of Package

Type	Quantity(pcs)
2512	4000
1206	5000

4. Peeling Test



Storage

- The ambient temperature shall between 5℃~35℃.
- The relative humidity recommended for storage is between 25%RH~75%RH.
- Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.